FDN360P-NBGT003B Datasheet

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DiGi Electronics Part Number	FDN360P-NBGT003B-DG
Manufacturer	onsemi
Manufacturer Product Number	FDN360P-NBGT003B
Description	MOSFET P-CH 30V 2A SOT23-3
Detailed Description	P-Channel 30 V 2A (Ta) 500mW (Ta) Surface Mount SOT-23-3

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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
FDN360P-NBGT003B	onsemi
Series:	Product Status:
PowerTrench®	Obsolete
FET Type:	Technology:
P-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
30 V	2A (Ta)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
4.5V, 10V	80mOhm @ 2A, 10V
Vgs(th) (Max) @ Id:	Gate Charge (Qg) (Max) @ Vgs:
3V @ 250µA	9 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±20V	298 pF @ 15 V
FET Feature:	Power Dissipation (Max):
-	500mW (Ta)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
SOT-23-3	TO-236-3, SC-59, SOT-23-3
Base Product Number:	
FDN360	

Environmental & Export classification

Moisture Sensitivity Level (MSL):	REACH Status:
1 (Unlimited)	REACH Unaffected
ECCN:	HTSUS:
EAR99	8541.21.0095

ON Semiconductor®

FDN360P

Single P-Channel, PowerTrench® MOSFET

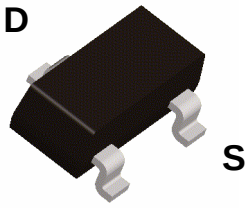
General Description

This P-Channel Logic Level MOSFET is produced using ON Semiconductor advanced Power Trench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

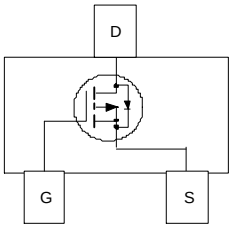
These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

Features

- –2 A, –30 V. $R_{DS(ON)}$ = 80 mΩ @ V_{GS} = –10 V
  $R_{DS(ON)}$ = 125 mΩ @ V_{GS} = –4.5 V
- Low gate charge (6.2 nC typical)
- High performance trench technology for extremely low $R_{DS(ON)}$.
- High power version of industry Standard SOT-23 package. Identical pin-out to SOT-23 with 30% higher power handling capability.
- These Devices are Pb-Free and are RoHS Compliant



SuperSOT™-3



Absolute Maximum Ratings

T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		–30	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Drain Current – Continuous	(Note 1a)	–2	A
	– Pulsed		–10	
P_D	Power Dissipation for Single Operation	(Note 1a)	0.5	W
		(Note 1b)	0.46	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		–55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
360	FDN360P	7''	8mm	3000 units

November-2018, Rev. 7

Publication Order Number:
FDN360P /D

Electrical Characteristics

T_A = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain–Source Breakdown Voltage	V_{GS} = 0 V, I_D = –250 μA	–30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = –250 μA, Referenced to 25°C		–22		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = –24V, V_{GS} = 0 V			–1	μA
		V_{DS} = –24V, V_{GS} = 0 V, T_J=55°C			–10	
I_{GSSF}	Gate–Body Leakage, Forward	V_{GS} = 20 V, V_{DS} = 0 V			100	nA
I_{GSSR}	Gate–Body Leakage, Reverse	V_{GS} = –20 V, V_{DS} = 0 V			–100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = –250 μA	–1	–1.9	–3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = –250 μA, Referenced to 25°C		4		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	V_{GS} = –10 V, I_D = –2 A		63	80	mΩ
		V_{GS} = –10 V, I_D = –2 A, T_J=125°C		90	136	
		V_{GS}= –4.5 V, I_D = –1.5A		100	125	
$I_{D(on)}$	On–State Drain Current	V_{GS} = –10 V, V_{DS} = –5 V	–10			A
g_{FS}	Forward Transconductance	V_{DS} = –5 V, I_D = –2 A		5		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = –15 V, V_{GS} = 0 V, f = 1.0 MHz		298		pF
C_{oss}	Output Capacitance			83		pF
C_{rss}	Reverse Transfer Capacitance			39		pF
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn–On Delay Time	V_{DD} = –15 V, I_D = –1 A, V_{GS} = –10 V, R_{GEN} = 6 Ω		6	12	ns
t_r	Turn–On Rise Time			13	23	ns
$t_{d(off)}$	Turn–Off Delay Time			11	20	ns
t_f	Turn–Off Fall Time			6	12	ns
Q_g	Total Gate Charge	V_{DS} = –15V, I_D = –3.6 A, V_{GS} = –10 V		6.2	9	nC
Q_{gs}	Gate–Source Charge			1		nC
Q_{gd}	Gate–Drain Charge			1.2		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain–Source Diode Forward Current				–0.42	A
V_{SD}	Drain–Source Diode Forward Voltage	V_{GS} = 0 V, I_S = –0.42 A (Note 2)		–0.8	–1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

a) 250°C/W when mounted on a 0.02 in² pad of 2 oz. copper.

b) 270°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

Typical Characteristics

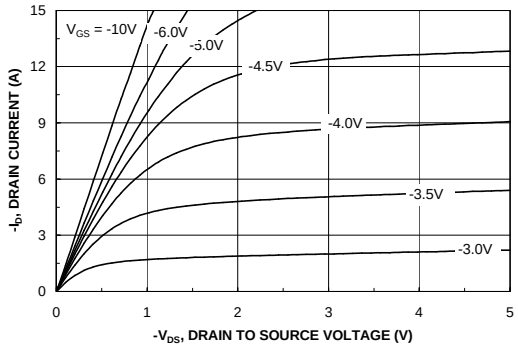


Figure 1. On-Region Characteristics.

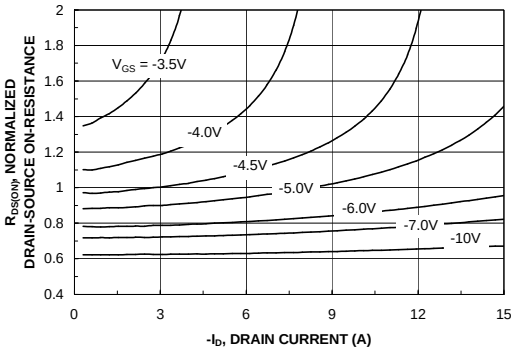


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

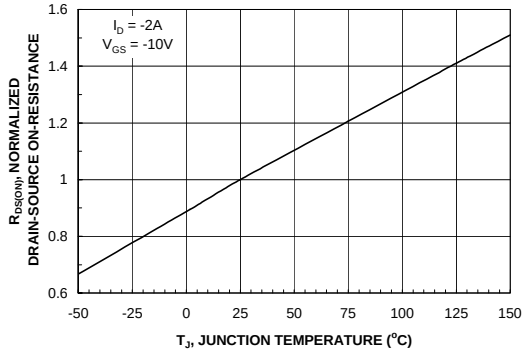


Figure 3. On-Resistance Variation with Temperature.

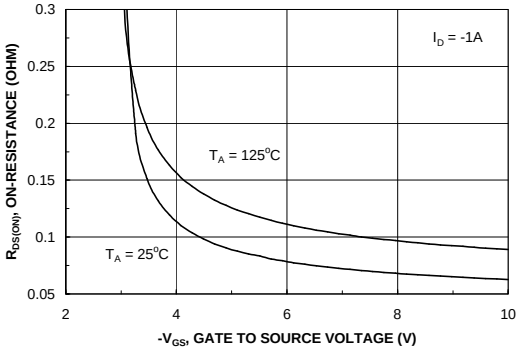


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

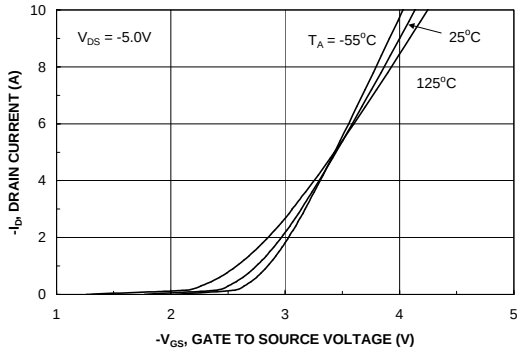


Figure 5. Transfer Characteristics.

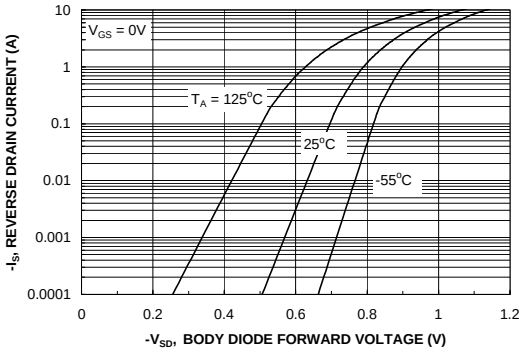


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

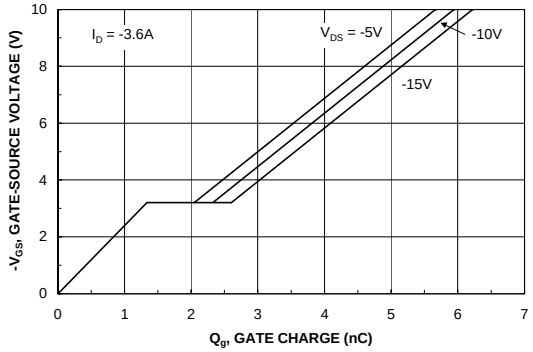


Figure 7. Gate Charge Characteristics.

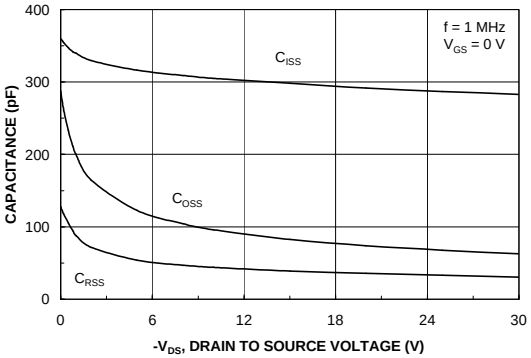


Figure 8. Capacitance Characteristics.

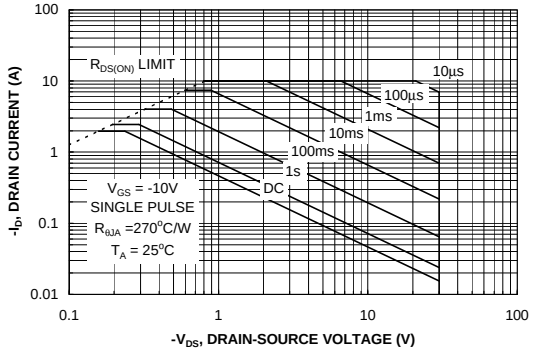


Figure 9. Maximum Safe Operating Area.

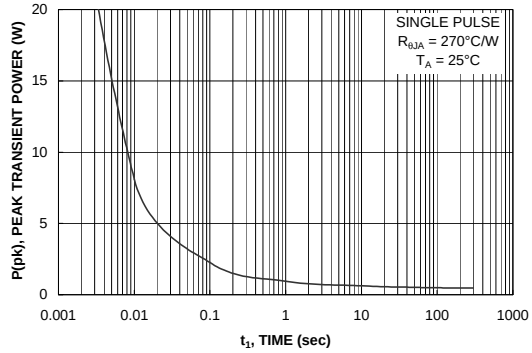


Figure 10. Single Pulse Maximum Power Dissipation.

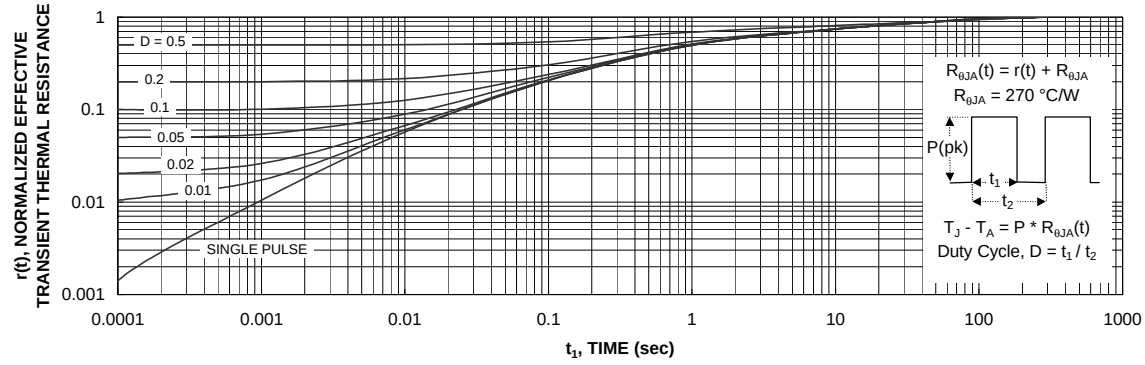


Figure 11. Transient Thermal Response Curve.

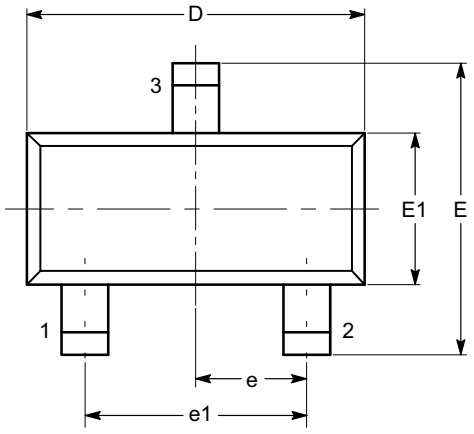
Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

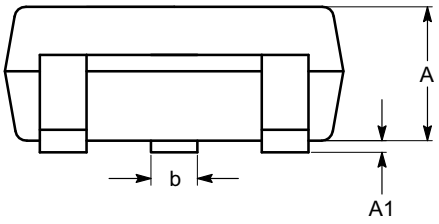
SOT−23, 3 Lead
CASE 527AG−01
ISSUE O

DATE 19 DEC 2008

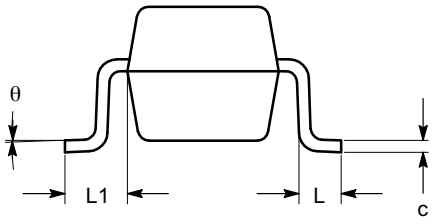


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.89		1.12
A1	0.013		0.10
b	0.37		0.50
c	0.085		0.18
D	2.80		3.04
E	2.10		2.64
E1	1.20		1.40
e	0.95 BSC		
e1	1.90 BSC		
L	0.40 REF		
L1	0.54 REF		
θ	0°		8°



SIDE VIEW



END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC TO-236.

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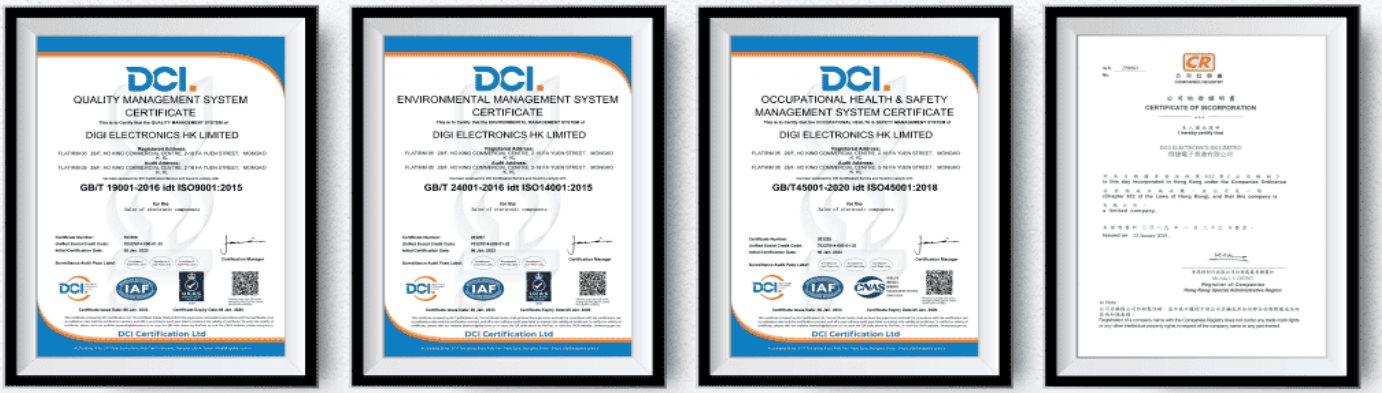

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